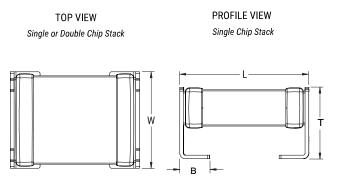
C2220C225K3N1C7186







Click here for the 3D model.

Dimensions	
L	6mm +/-0.5mm
W	5mm +/-0.5mm
T	3.5mm +/-0.30mm
В	1.6mm +/-0.3mm
Ь	1.011111 7/-0.311111

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	300

General Information	
Series	KPS SMD Comm X8L HT150C
Style	Stacked Chip
Description	SMD, MLCC, Stacked, Single Chip, High Temperature
Features	High Temperature
RoHS	Yes
Termination	Tin
AEC-Q200	No
Typical Component Weight	410 mg
Chip Size	2220-1
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	2.2 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	10%
Voltage DC	25 VDC
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8L
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	+15% (-55C to +125C), +15/-40% (125C to 150C), 1kHz 1.0Vrms
Dissipation Factor	2.5% 1 kHz 1.0 Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	227.3 MOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

Generated 06/07/2025 © 2006 - 2025 YAGEO